

IEC-2023

9<sup>th</sup> International Engineering Conference



“A new Trend for Research and Development in Engineering”

## Letter of Appreciation

Date: 22/02/2023

Dear, Mrs. Nazik Khalid Hassan  
(Erbil Polytechnic University, Iraq)

We wish to genuinely thank you for reviewing the 1 article (listed below) submitted on 9<sup>th</sup> International Engineering Conference (IEC2023), jointly organized by Tishk International University and Erbil Polytechnic University, and technically sponsored by IEEE represented by IEEE Iraq Section.

Thanks to your contributions, which help us to organize such a great international engineering conference hosted the researchers from all over the world and provide a dynamic and fruitful environment that fosters the scientists, researchers, and scholars in the computer and civil engineering fields.

Thank you again for all of your generous support, we could not have done it without you!

We look forward to your contribution again next year.

List of articles:

Paper ID	Paper Name
1570870087	Exp. Study of Hollow EPS Blocks Incorporation on Concrete Walls Under Axial Load

Sincerely,

Dr. Abubakar M. Ashir  
IEC2023 Chair  
Tishk International University

Dr. Ganjeena J. Khoshnaw  
IEC2023 Co-Chair  
Erbil Polytechnic University

